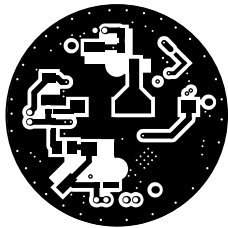
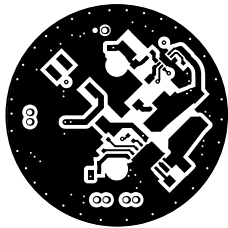


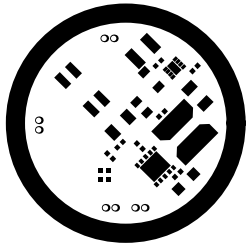
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0021	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Mtp Solder Information			
PLOT NAME = Top Solder Mask	GENERATED : 9/27/2013 12:30:53 PM	TEXAS INSTRUMENTS	



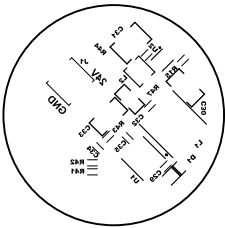
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LAYER NAME = Top Layer Top Layer Information			
PLOT NAME = Top Layer	GENERATED : 9/27/2013 12:30:53 PM		TEXAS INSTRUMENTS



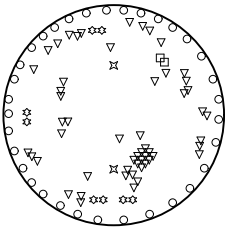
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0021	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/27/2013 12:30:54 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0021	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder Mask			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/27/2013 12:30:54 PM	TEXAS INSTRUMENTS	



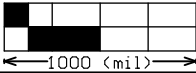
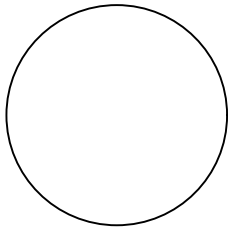
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	SAT0021	REV:	E3	SUN REV:	Not In VersionControl
LAYER NAME =	Bottom Overlay					
PLOT NAME =	Bottom Overlay		GENERATED	: 9/27/2013 12:30:55 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	54	10mil (0.254mm)	PTH	Round
□	2	11.811mil (0.3mm)	PTH	Round
○	33	12mil (0.305mm)	PTH	Round
☆	8	28mil (0.711mm)	PTH	Round
⌘	2	78.74mil (2mm)	PTH	Round
99 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SAT0021	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	Drill Drawing Information		
PLOT NAME = Drill Drawing	GENERATED : 9/27/2013 12:30:55 PM		TEXAS INSTRUMENTS



1000 (mil)

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:	SAT0021	REV:	E3	SUN REV:	Not In VersionControl
LAYER NAME = M21 Board Dimensions						
PLOT NAME = Board Dimensions	GENERATED	: 9/27/2013 12:30:56 PM			TEXAS INSTRUMENTS	

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